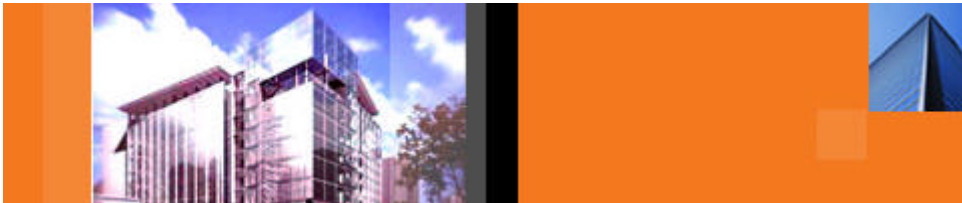


New Investment

New Plant - Geared for 6 layers and above



To let you take further advantage of our high layer count solutions, we have been breaking ground with our new plant expansion.

New Plant Capacity

A new eight-storey, 400K sq. ft. shop floor facility will bring an addition of 300K sq. ft. high layer count capacity in Phase I in the second quarter of 2003.

A total of 800K sq. ft. capacity will be added in 2004 when the whole plant come into full operation, and will eventually boost our total monthly capacity to 2.3M sq. ft. per month.

Total Investment

A total of about HK\$600 millions (US\$77.1 millions) will be invested into this expansion project. New equipment includes:

- Horizontal Pulse Plating Line
- Electrolytic Gold Plating
- Immersion Tin Line
- Laser Direct Imaging
- Copper Direct Laser Drill
- Vertical Pulse Plating Lines
- Automated Drill Optimization
- CAT Portable System
- IST Reliability Tester
- Fineline Etching Modules
- Inspire Automated AOI
- High Speed Flying Probe Units
- High Density Universal Tester Unit
- Multiline Pin-slot Tooling
- High Speed Drilling Units producing 8 mil vias